Sharon Nai

List of Publications by Citations

61 papers	1,524 citations	21 h-index	38 g-index
69 ext. papers	1,701 ext. citations	3.2 avg, IF	4.52 L-index

#	Paper	IF	Citations
61	Improving the performance of lead-free solder reinforced with multi-walled carbon nanotubes. *Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing* , **2006**, 423, 166-169	5.3	118
60	Influence of ceramic reinforcements on the wettability and mechanical properties of novel lead-free solder composites. *Thin Solid Films*, **2006**, 504, 401-404	2.2	116
59	Interfacial intermetallic growth and shear strength of lead-free composite solder joints. *Journal of Alloys and Compounds*, **2009**, 473, 100-106	5.7	114
58	Low temperature wafer anodic bonding. *Journal of Micromechanics and Microengineering*, **2003**, 13, 217-222	2	103
57	Spatial and geometrical-based characterization of microstructure and microhardness for an electron beam melted Ti6Al4V component. *Materials and Design*, **2016**, 95, 287-295	8.1	87
56	Effect of Carbon Nanotubes on the Shear Strength and Electrical Resistivity of a Lead-Free Solder. *Journal of Electronic Materials*, **2008**, 37, 515-522	1.9	85
55	Microhardness and microstructure evolution of TiB2 reinforced Inconel 625/TiB2 composite produced by selective laser melting. *Optics and Laser Technology*, **2016**, 80, 186-195	4.2	78
54	Effect of carbon nanotubes on corrosion of MgCNT composites. *Corrosion Science*, **2010**, 52, 1551-1553	6.8	64
53	Development of a SnAgCu solder reinforced with Ni-coated carbon nanotubes. *Journal of Materials Science: Materials in Electronics*, **2011**, 22, 315-322	2.1	63
52	Interfacial reaction and shear strength of Ni-coated carbon nanotubes reinforced SnAgCu solder joints during thermal cycling. *Intermetallics*, **2012**, 31, 72-78	3.5	61
51	Development of lead-free Sn-3.5Ag/SnO2 nanocomposite solders. *Journal of Materials Science: Materials in Electronics*, **2009**, 20, 571-576	2.1	46
50	Reinforcements at nanometer length scale and the electrical resistivity of lead-free solders. *Journal of Alloys and Compounds*, **2009**, 478, 458-461	5.7	45
49	Temperature Dependence of Creep and Hardness of Sn-Ag-Cu Lead-Free Solder. *Journal of Electronic Materials*, **2010**, 39, 223-229	1.9	45
48	Development of high strength SnCu solder using copper particles at nanolength scale. *Journal of Alloys and Compounds*, **2009**, 476, 199-206	5.7	41
47	Using Microwave-Assisted Powder Metallurgy Route and Nano-size Reinforcements to Develop High-Strength Solder Composites. *Journal of Materials Engineering and Performance*, **2010**, 19, 335-341	1.6	39
46	Micro-structure and Mechanical Properties of Nano-TiC Reinforced Inconel 625 Deposited using LAAM. *Physics Procedia*, **2013**, 41, 828-834		32
45	DFT Study on Nano Structures of Sn/CNT Complex for Potential Li-Ion Battery Application. *Journal of Physical Chemistry C*, **2009**, 113, 14015-14019	3.8	30

44	Enhanced welding efficiency in laser welding of highly reflective pure copper. *Journal of Materials Processing Technology*, **2015**, 216, 287-293	5.3	28
43	Using carbon nanotubes to enhance creep performance of lead free solder. *Materials Science and Technology*, **2008**, 24, 443-448	1.5	25
42	A modified constitutive model for creep of Sn□3.5Ag□0.7Cu solder joints. *Journal Physics D: Applied Physics*, **2009**, 42, 125411	3	23
41	Effect of Building Height on Microstructure and Mechanical Properties of Big-Sized Ti-6Al-4V Plate Fabricated by Electron Beam Melting. *MATEC Web of Conferences*, **2015**, 30, 02001	0.3	22
40	Glass-to-glass anodic bonding process and electrostatic force. *Thin Solid Films*, **2004**, 462-463, 487-491	2.2	20
39	Characterization of nanoparticle mixed 316 L powder for additive manufacturing. *Journal of Materials Science and Technology*, **2020**, 47, 162-168	9.1	18
38	Effect of Ni-Coated Carbon Nanotubes on Interfacial Reaction and Shear Strength of Sn-Ag-Cu Solder Joints. *Journal of Electronic Materials*, **2012**, 41, 2478-2486	1.9	18
37	Synthesis and wear characterization of Al based, free standing functionally graded materials: effects of different matrix compositions. *Composites Science and Technology*, **2003**, 63, 1895-1909	8.6	18
36	Low temperature glass-to-glass wafer bonding. *IEEE Transactions on Advanced Packaging*, **2003**, 26, 289-294		18
35	Influence of applied load on vacuum wafer bonding at low temperature. *Sensors and Actuators A: Physical*, **2004**, 115, 67-72	3.9	15
34	Synthesis and wear of Al based, free standing functionally gradient materials: effects of different reinforcements. *Materials Science and Technology*, **2004**, 20, 57-67	1.5	14
33	Synthesis of Al/SiC based functionally gradient materials using technique of gradient slurry disintegration and deposition: effect of stirring speed. *Materials Science and Technology*, **2002**, 18, 633-641	1.5	12
32	Effect of Amount of Cu on the Intermetallic Layer Thickness Between Sn-Cu Solders and Cu Substrates. *Journal of Electronic Materials*, **2009**, 38, 2479-2488	1.9	11
31	Effect of Ni-Coated Carbon Nanotubes on the Corrosion Behavior of Sn-Ag-Cu Solder. *Journal of Electronic Materials*, **2013**, 42, 3559-3566	1.9	10
30	Development of Lead-Free Solder Composites Containing Nanosized Hybrid (ZrO2 + 8 mol.% Y2O3) Particulates. *Solid State Phenomena*, **2006**, 111, 59-62	0.4	10
29	Kinetics of interface reaction and intermetallics growth of Sn-3.5Ag-0.7Cu/Au/Ni/Cu system under isothermal aging. *Journal of Materials Science*, **2004**, 39, 1095-1099	4.3	10
28	DEVELOPMENT OF NOVEL LEAD-FREE SOLDER COMPOSITES USING CARBON NANOTUBE REINFORCEMENTS. *International Journal of Nanoscience*, **2005**, 04, 423-429	0.6	10
27	INDENTATION SIZE EFFECT ON THE CREEP BEHAVIOR OF A SnAgCu SOLDER. *International Journal of Modern Physics B*, **2010**, 24, 267-275	1.1	9

26	Synthesis and characterization of free standing, bulk Al/SiCp functionally gradient materials: effects of different stirrer geometries. *Materials Research Bulletin*, **2003**, 38, 1573-1589	5.1	7
25	Microstructure and damping characteristics of Mg and its composites containing metastable Al85Ti15 particle. *Journal of Composite Materials*, **2016**, 50, 2565-2573	2.7	6
24	Comparative Eco-efficiency Analyses of Copper to Copper Bonding Technologies. *Procedia CIRP*, **2014**, 15, 96-104	1.8	6
23	Integrating copper at the nanometer length scale with Sn□□Ag solder to develop high performance nanocomposites. *Materials Science and Technology*, **2009**, 25, 1258-1264	1.5	5
22	Advanced high density interconnect materials and techniques **2009**,		5
21	Enhancing the properties of a lead-free solder with the addition of Ni-coated carbon nanotubes **2009**,		5
20	Silicon-to-silicon wafer bonding with gold as intermediate layer		5
19	NANOMECHANICAL PROPERTIES OF A Sn□Ag□Cu SOLDER REINFORCED WITH Ni-COATED CARBON NANOTUBES. *International Journal of Nanoscience*, **2010**, 09, 283-287	0.6	4
18	Suppressing intermetallic compound growth in SnAgCu solder joints with addition of carbon nanotubes **2008**,		4
17	Low-temperature sol□el intermediate layer wafer bonding. *Thin Solid Films*, **2006**, 496, 560-565	2.2	3
16	Effect of Ni-coated carbon nanotubes on the microstructure and properties of a Sn-Ag-Cu solder **2010**,		2
15	Development of Lead-Free Nanocomposite Solders Using Oxide Based Reinforcement **2008**,		2
14	Enhancing the Performance of Sn-Ag-Cu Solder With the Addition of Titanium Diboride Particulates **2004**, 315		2
13	Enhanced Mechanical Properties of Poly(Vinyl Alcohol) Nanofibers With Molecular Level Dispersed Graphene **2012**,		1
12	Indentation creep and hardness of a Sn-Ag-Cu solder reinforced with Ni-coated carbon nanotubes **2010**,		1
11	Effect of Ni-coated carbon nanotubes on interfacial intermetallic layer growth **2009**,		1
10	Utilizing energy efficient microwave sintering to significantly enhance the tensile response of a lead-free solder. *Journal Physics D: Applied Physics*, **2009**, 42, 015404	3	1
9	Indentation Size Effect on the Hardness of a Sn-Ag-Cu Solder **2009**,		1

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8	A New Creep Model for SnAgCu Lead-Free Composite Solders: Incorporating Back Stress **2008**,	1
7	Effect of Presence of Multi-Walled Carbon Nanotubes on the Creep Properties of Sn-Ag-Cu Solder **2006**, 161	1
6	Influence of Reinforcements on the Electrical Resistivity of Novel Sn-Ag-Cu Composite Solder **2007**, 39	1
5	Development of Advanced Lead-Free Solder Based Interconnect Materials Containing Nanosized Y2O3 Particulates **2005**,	1
4	Wafer Level Packaging of RF MEMS for Flip Chip Assembly **2003**, 119	
3	Low Temperature Wafer Bonding Process Using Sol-Gel Intermediate Layer **2004**, 309	
2	Solder Joint Technology **2015**, 713-763	
1	Solid State Microjoining Processes in Manufacturing **2015**, 641-683	